FORM PTO- 1595 (Rev. 6-93) OMB No. 0651-0011 (exp 4/94) To the Honorable Commissioner of Patent 1. Name of conveying party(ies): Brian F. Gordon Paul D. Shirley Additional name(s) of conveying party(ies) attached? Yes No 3. Nature of conveyar ce: X Assignment Merger Security Agreement Change of Name Other Execution Date: September 16, 1999 4. Application number(s) or patent number(s): If this document is being filed together with a new application	ached original documents or copy thereof. ass of receiving party(ies): Name: Micron Technology, Inc. Internal Address: Street Address: 8000 South Federal Way City: Boise State: ID ZIP: 83706-9632 Additional name(s) & address(es) attached?
A Patent Application No.(s)	B. Patent No.(s)
5. Name and address of party to whom correspondence concerning document should be mailed: Name: Donald Brent Kenady Internal Address: Wells, St. John, Roberts, Gregory & Matkin P.S. 0/14/1999 PSTRMBAC 000000033 09410969	6. Total number of applications and patents involved: 7. Total fee (37 CFR 3.41)
Street Address: 601 West First Ave., Suite 1300	8. Deposit account number: (Attach duplicate copy of this page if paying by deposit account)
9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document. Donald Brent K.enady Name of Person Signing Total number of pages including cover sheet, attachments, and document:	

Mail documents to be recorded with required cover sheet information to: Commissioner of Patents & Trademarks, Box Assignments Washington, D.C. 20231

(Form PTO--1595--Recordation Form Cover Sheet - page 1 of 3)

ASSIGNMENT

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PARTIES TO THE ASSIGNMENT:

INVENTORS:

Brian F. Gordon

Paul D. Shirley

ASSIGNEE:

Micron Technology, Inc. Corporation of the State of Delaware 8000 South Federal Way Boise, Idaho 83706-9632

BACKGROUND OF THIS ASSIGNMENT:

INVENTORS have conceived certain new and useful inventions disclosed in a United States patent application titled "Substrate Coating Apparatus and Semiconductor Processing Method of Improving Uniformity of Liquid Deposition".

MICRON TECHNOLOGY, INC. desires to acquire the entire right, title and interest in said inventions and with respect to any Letters Patent that may be granted with respect to the inventions in both the United States and in all foreign countries.

THE PARTIES AGREE AS FOLLOWS:

In consideration of good and valuable consideration, the receipt sufficiency and adequacy of which is hereby acknowledged, INVENTORS hereby sell, assign and transfer to MICRON TECHNOLOGY, INC. the entire right, title and interest in the above-identified application executed

currently with this assignment and to any reissues, renewals, divisions or continuations thereof, and hereby authorizes the Commissioner of Patents and Trademarks to issue such Letters Patent to MICRON TECHNOLOGY, INC., for the sole use of MICRON TECHNOLOGY, INC., its successors or assigns.

INVENTORS further agree to execute, at the request and expense of MICRON TECHNOLOGY, INC. such other formal documents as may be required to fully convey the interest transferred herein and will similarly execute any application papers required for the filing of any division, continuation, renewal or reissue of the patent application or resulting Letters Patent; and will generally do everything necessary or desirable to obtain and enforce proper protection for the inventions assigned hereby.

INVENTORS further assign to MICRON TECHNOLOGY, INC. the whole right, title and interest in the inventions disclosed in the application throughout all countries foreign to the United States. MICRON TECHNOLOGY, INC. is hereby authorized to apply for patents relating to the inventions in its own name in countries where such procedure is proper; to claim the benefit of the International Convention; to file and prosecute International Applications relating to the inventions under the Patent Cooperation Treaty; and to file and prosecute applications relating to the inventions under the European Patent Convention. INVENTORS agree to execute applications relating to the inventions in those countries and under those conventions where

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it is necessary that the same be executed by the inventor, and to execute assignments of such applications and the resulting Letters Patent to MICRON TECHNOLOGY, INC. as well as all other necessary papers in relation to such applications and Letters Patent.

INVENTORS further warrant and covenant that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been or will be made to others by the undersigned, and that the full rights to convey the same as herein expressed is possessed by the undersigned.

To be binding on the heirs, assigns, representatives and successors of the undersigned and extend to the successors, assigns and nominees of the Assignees.

_____ Date: 9-16-99 (Signature) BRIAN F. GORDON

State of County of

BEFORE ME, this day of personally appeared the above-named inventor, to me known to be the person who is described in and who executed the foregoing assignment instrument and acknowledged to me that he/she executed the same of his/her own free will for the purpose therein expressed.



Notary or Consular Officer My Commission Expires:

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